Week 4 MIS-5903 Domain 3: Security Architecture & Engineering	
https://community.mis.temple.e du/mis5903sec711summer2021	- And the state of
Last Revised 6/01/21	
	i

ISO/IEC 42010:2011 Vocabulary

- Architecture
 Organization of a system/components
 Relationship between components and environment
 Principles guiding design and evolution
 Architecture Description (AD) documents in a formal manner
- Stakeholder have interests in the system

 - Users
 Maintenance staff, operators
 Developers
 Suppliers
- View Representation of system from perspective of concerns
- Viewpoint Specification of the conventions for constructing and using a view
 Template from which to develop individual views (purposes, audience for a view, techniques)

2

Example Viewpoints Logical • Physical • Structural • Behavioral Management • Cost • Security Model Kind Architecture Model

Centra	Processing	Unit
--------	------------	------

- Registers (locate instructions, data in memory)
 General variables, temporary work results
 Special program counter, stack pointer, program status word
 User Mode [aka problem state)
 Privileged Mode (aka kernel or supervisor)
- Control Unit
 Control Bus
 Data Bus (retrieve data)
 Address Bus (pass from CPU to RAM, ROM, I/O)

 Address Bus (pass from CPU to RAM, ROM, I/O)
- Arithmetic Logit Unit (ALU)
- Multi-tasking processor completes individual tasks

Multiprocessing
 Symmetric mode (scheduler determines and balances processor loads)
 Asymmetric mode (dedicated processor for user time-sensitive threads)

4

Memory – Random Access Memory (RAM)

- Static RAM does not require refreshing; used for cache.
- Dynamic:
 - Synchronous DRAM synchronized signal input and output
 Extended Data Out DRAM access next block of data ("look ahead")

 - Burst EDO SDRAM reads and sends up to four memory addresses.
 - Double Data Rate SDRAM utilizes both rising and falling cycles of a clock

5

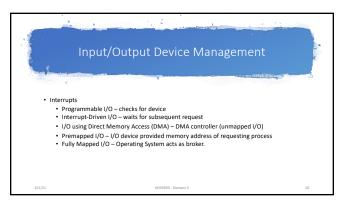
Memory – Other Types

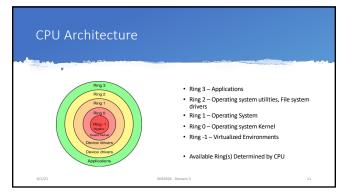
- Read Only Memory
 - Software stored in ROM referred to as firmware
 Programmable Read-Only Memory (only once)

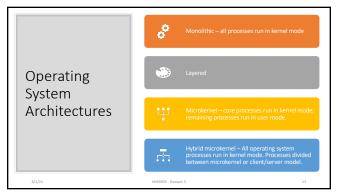
 - $\bullet \ \, \text{Erasable Programmable Read-Only Memory (EPROM)} \text{ultraviolet} \\$
 - Electrically Erasable Programmable Read-Only Memory (EEPROM)
- Flash Memory
 - SD-Card is an example
- Cache Memory
 - Level 3 on motherboard
 - Level 1, Level 2 inside processor/controller.

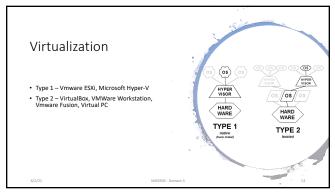
		_	
	Memory Issues	_	
	- <u></u>	_	
	Mapping Physical memory is an absolute address		
	Indexed addresses used by software are logical addresses. Duffer Outsides.	_	
	Buffer Overflow Programmer doesn't check input value type	_	
	Memory Leaks		
	 Operating System becomes "starved" Memory no longer in use/needed not released. 	_	
		-	
		_	
	6/1/21 MISS903 - Domain 3 7]	
7			
]	
	Operating Systems	_	
		_	
	 Process Management Cooperative multitasking (Windows 3.x, early Mac) – controlled by process 		
	Preemptive multitasking – controlled by operating system	_	
	Thread Management – portions of process	_	
	Process Scheduling – affinity levels Process Activity		
	Process isolation	_	
	 If not encapsulated, could accept malicious instructions Time Multiplexing – processes use same resources 	_	
	6/1/21 MISS903 - Domain 3 8] -	
8			
		1	
	Operating System Memory Management	_	
	Operating System Memory Management		
	• Goals:		
	 Provide abstraction level for programmers Maximize performance with limited memory 	-	
	Protect OS and applications in memory		
	Relocation: swap from RAM to hard drive. Provide Pointers	-	
	Protection: limit processes to assigned memory segments Sharing: allow shared memory segments	-	
	Logical Organization: Segment all memory types		
	Physical Organization: Separate memory space for OS versus apps.	-	

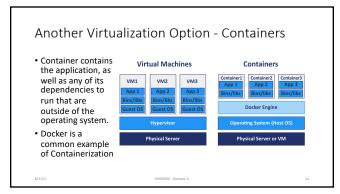
_



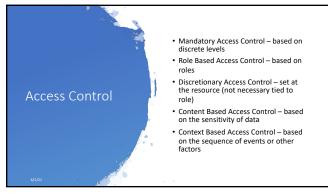


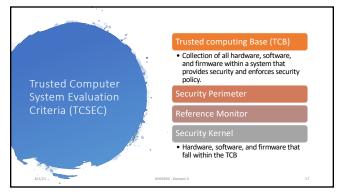


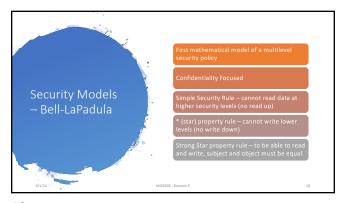


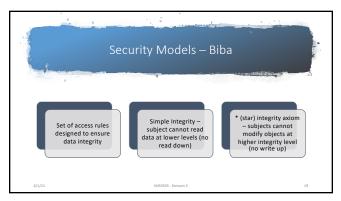


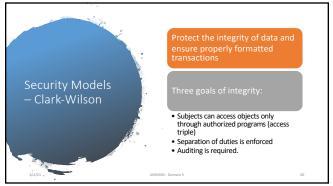


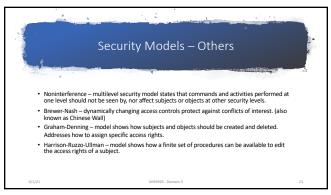


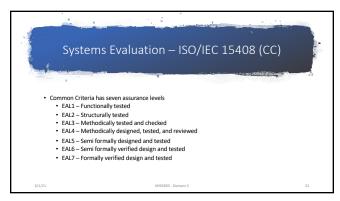


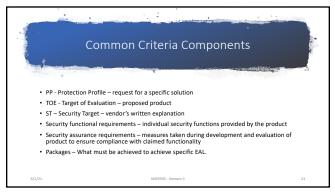






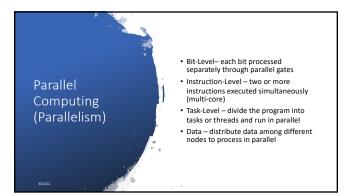


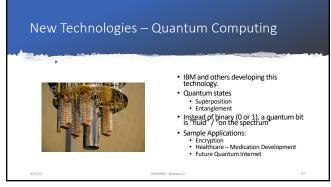




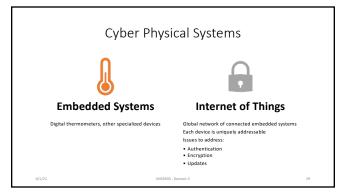




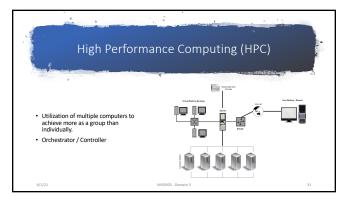






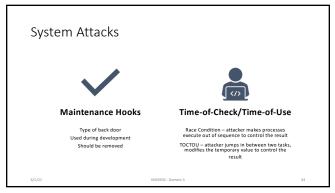


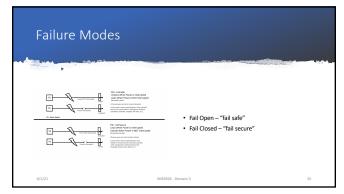


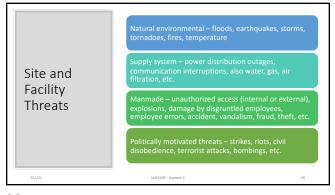


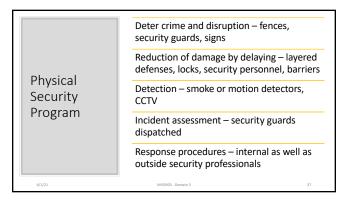
















	Resistance to forcible entry
	Emergency Marking
	Placement
Duilding	Locked or Controlled
Building a Facility -	Alarms
Doors	Secure hinges
Doors	Directional opening
	Electric door locks (fail safe)
	Type of glass – shatterproof or bulletproof
	Hollow-Core or Solid-Core
6/1/21	MISS903 - Domain 3 40



	Translucent or opaque	
	Alarms	
D 11.11	Placement	
Building a Facility –	Accessibility to intruders	
Windows	Strength - Shatterproof?	
VVIIIdovV3	Standard Tempered	
	Acrylic	
	Wired	
	Laminated Solar or Security film	
	•	
6/1/21	MISS903 - Domain 3	42

	Positive Air Pressure	
	Protected intake vents	
Duilding a	Dedicated power lines	
Building a Facility –	Emergency shutoff valve and switches	
HVAC	Placement	
	Considerations:	
	Computer systems: 175 degrees Magnetic Storage Devices: 100 degrees Paper Products: 350 degrees	
6/1/21	MISS903 - Domain 3	43

Designing a Facility Supplies Designing a Facility Supplies Electromagnetic Interference (EMI) Pagion Piper Online UPS / Generators Water & Gas Shutoff valves – labeled for visibility Positive flow (material flows out of building) Placement – properly located

44

Electric Power Fluctuations Electric Power Fluctuations Electric Power Fluctuations Electric Power Fluctuations Fault – momentary Blackout – prolonged, complete loss Degradation: Sag/Dip – momentary – from one cycle to a few seconds Brownout – prolonged below normal voltage In-Rush current – initial surge required to start a load

Desig	gning a Facility – Fire Detection of Suppression	&
• Smoke • Heat / Rati • Placement of s	sensors and detectors e of Rise suppression systems tors and suppression agents	
6/1/21	MISS903 - Domain 3	46

Class	Type of Fire	Elements	Suppression
Α	Common combustibles	Wood products, paper, and laminates	Water, foam
В	Liquid	Petroleum products and coolants	Gas, CO2, foam, dry powders
С	Electrical	Electrical equipment and wires	Gas, CO2, dry powders
D	Combustible metals	Magnesium, sodium, potassium	Dry powder

Combustion Element	Suppression Method	How Suppression Works
Fuel	Soda acid	Removes fuel
Oxygen	Carbon dioxide	Removes oxygen
Temperature	Water	Reduces temperature
Chemical combustion	Gas – Halon substitute (FM-200)	Interferes with the chemical reasons between elements

